Rochester Electronics

Datasheet

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
    - Class Q Military
    - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

    - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

SN74LS166

8-Bit Shift Registers

The SN74LS166 is an 8-Bit Shift Register. Designed with all inputs buffered, the drive requirements are lowered to one 74LS standard load. By utilizing input clamping diodes, switching transients are minimized and system design simplified.

The LS166 is a parallel-in or serial-in, serial-out shift register and has a complexity of 77 equivalent gates with gated clock inputs and an overriding clear input. The shift/load input establishes the parallel-in or serial-in mode. When high, this input enables the serial data input and couples the eight flip-flops for serial shifting with each clock pulse. Synchronous loading occurs on the next clock pulse when this is low and the parallel data inputs are enabled. Serial data flow is inhibited during parallel loading. Clocking is done on the low-to-high level edge of the clock pulse via a two input positive NOR gate, which permits one input to be used as a clock enable or clock inhibit function. Clocking is inhibited when either of the clock inputs are held high, holding either input low enables the other clock input. This will allow the system clock to be free running and the register stopped on command with the other clock input. A change from low-to-high on the clock inhibit input should only be done when the clock input is high. A buffered direct clear input overrides all other inputs, including the clock, and sets all flip-flops to zero.

- Synchronous Load
- Direct Overriding Clear
- Parallel to Serial Conversion

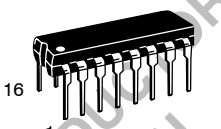
GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Typ	Max	Unit
V_{CC}	Supply Voltage	4.75	5.0	5.25	V
T_A	Operating Ambient Temperature Range	0	25	70	°C
I_{OH}	Output Current – High			–0.4	mA
I_{OL}	Output Current – Low			8.0	mA

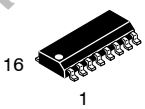
ON Semiconductor™

http://onsemi.com

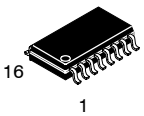
LOW POWER SCHOTTKY



PLASTIC
N SUFFIX
CASE 648



SOIC
D SUFFIX
CASE 751B

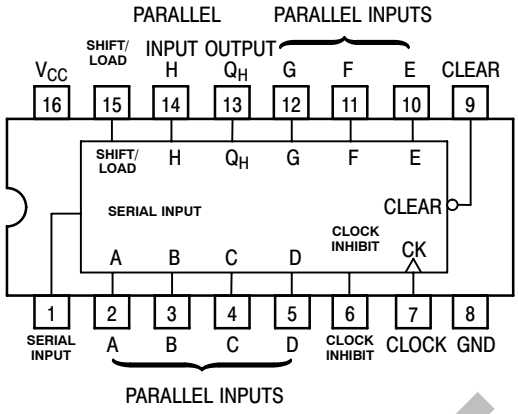


SOEIAJ
M SUFFIX
CASE 966

ORDERING INFORMATION

Device	Package	Shipping
SN74LS166N	16 Pin DIP	2000 Units/Box
SN74LS166D	SOIC–16	38 Units/Rail
SN74LS166DR2	SOIC–16	2500/Tape & Reel
SN74LS166M	SOEIAJ–16	See Note 1
SN74LS166MEL	SOEIAJ–16	See Note 1

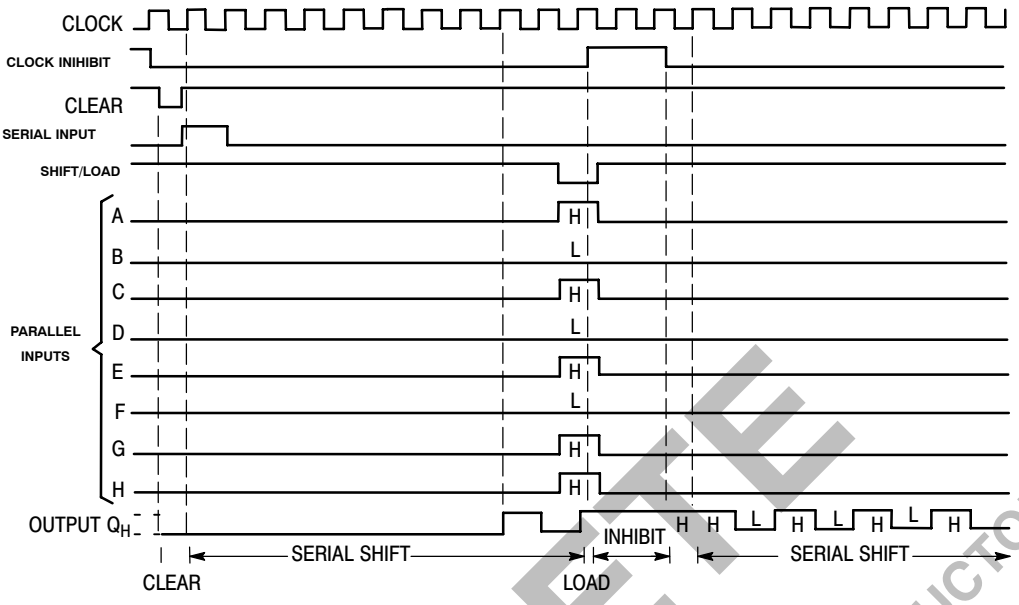
1. For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

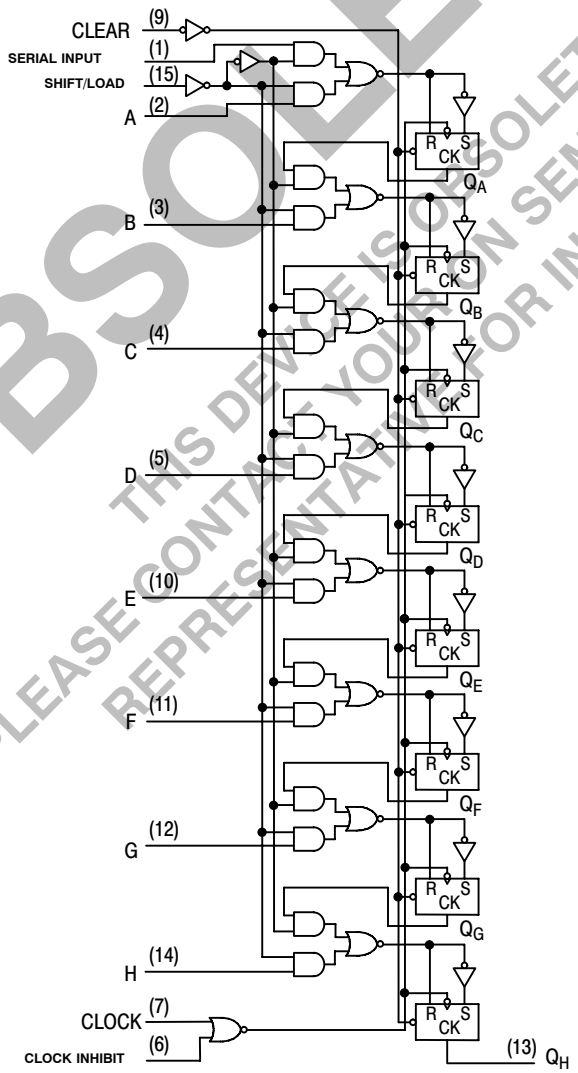


FUNCTION TABLE

INPUTS						INTERNAL OUTPUTS		OUTPUT Q_H
CLEAR	SHIFT/ LOAD	CLOCK INHIBIT	CLOCK	SERIAL	PARALLEL A . . . H	Q_A	Q_B	
L	X	X	X	X	X	L	L	L
H	X	L	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	L	L	↑	X	a . . . h	a	b	h
H	H	L	↑	H	X	H	Q_{An}	Q_{Gn}
H	H	L	↑	L	X	L	Q_{An}	Q_{Gn}
H	X	H	↑	X	X	Q_{A0}	Q_{B0}	Q_{H0}

Typical Clear, Shift, Load, Inhibit, and Shift Sequences





DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

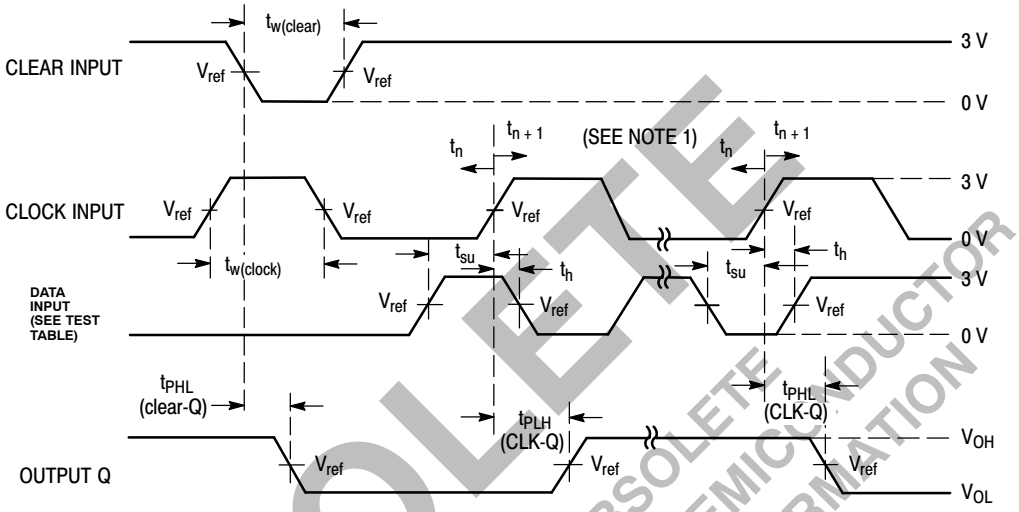
Symbol	Parameter	Limits			Unit	Test Conditions	
		Min	Typ	Max			
V_{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs	
V_{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs	
V_{IK}	Input Clamp Diode Voltage		−0.65	−1.5	V	V_{CC} = MIN, I_{IN} = −18 mA	
V_{OH}	Output HIGH Voltage	2.7	3.5		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
V_{OL}	Output LOW Voltage		0.25	0.4	V	I_{OL} = 4.0 mA	V_{CC} = V_{CC} MIN, V_{IN} = V_{IL} or V_{IH} per Truth Table
			0.35	0.5	V	I_{OL} = 8.0 mA	
I_{IH}	Input HIGH Current			20	μA	V_{CC} = MAX, V_{IN} = 2.7 V	
				0.1	mA	V_{CC} = MAX, V_{IN} = 7.0 V	
I_{IL}	Input LOW Current			−0.4	mA	V_{CC} = MAX, V_{IN} = 0.4 V	
I_{OS}	Short Circuit Current (Note 2)	−20		−100	mA	V_{CC} = MAX	
I_{CC}	Power Supply Current			38	mA	V_{CC} = MAX	

2. Not more than one output should be shorted at a time, nor for more than 1 second.

TEST TABLE FOR SYNCHRONOUS INPUTS

DATA INPUT FOR TEST	SHIFT/LOAD	OUTPUT TESTED
H	0 V	Q_H at t_{n+1}
Serial Input	4.5 V	Q_H at t_{n+8}

AC WAVEFORMS



NOTE 1. t_n = bit time before clocking transition
t_{n+1} = bit time after one clocking transition
t_{n+8} = bit time after eight clocking transition
LS166 V_{ref} = 1.3 V.

AC CHARACTERISTICS (T_A = 25°C)

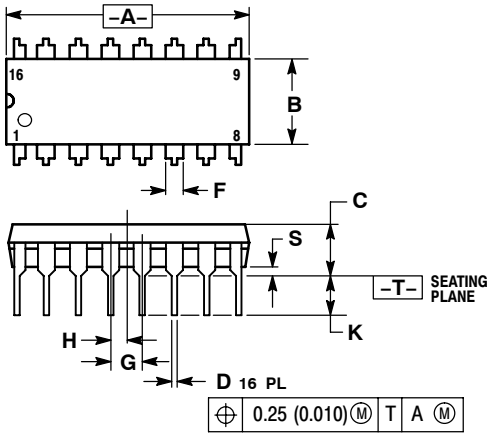
Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f_{MAX}	Maximum Clock Frequency	25	35		MHz	V_{CC} = 5.0 V C_L = 15 pF
t_{PHL}	Clear to Output		19	30	ns	
t_{PLH} t_{PHL}	Clock to Output		23 24	35 35	ns	

AC SETUP REQUIREMENTS (T_A = 25°C)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
t_W	Clock Clear Pulse Width	30			ns	V_{CC} = 5.0 V
t_s	Mode Control Setup Time	30			ns	
t_s	Data Setup Time	20			ns	
t_h	Hold Time, Any Input	15			ns	

PACKAGE DIMENSIONS

N SUFFIX
PLASTIC PACKAGE
CASE 648−08
ISSUE R

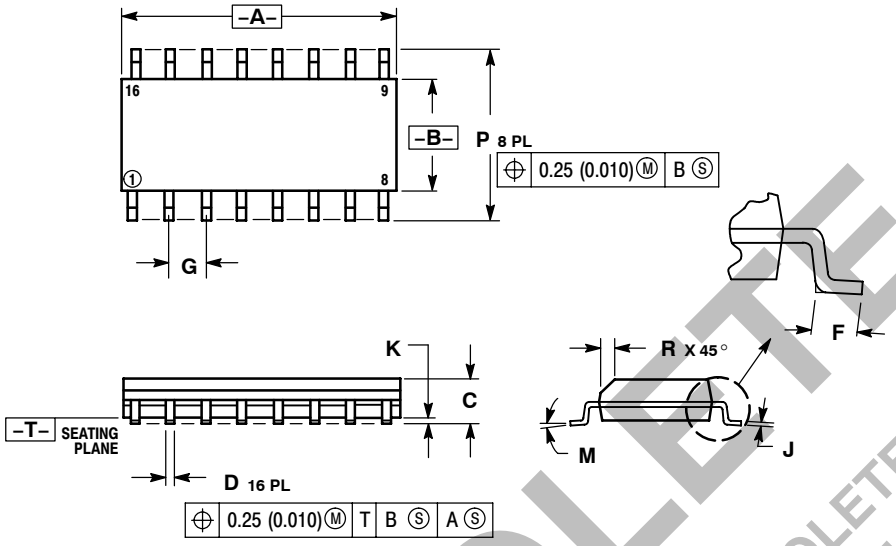


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B–05
ISSUE J

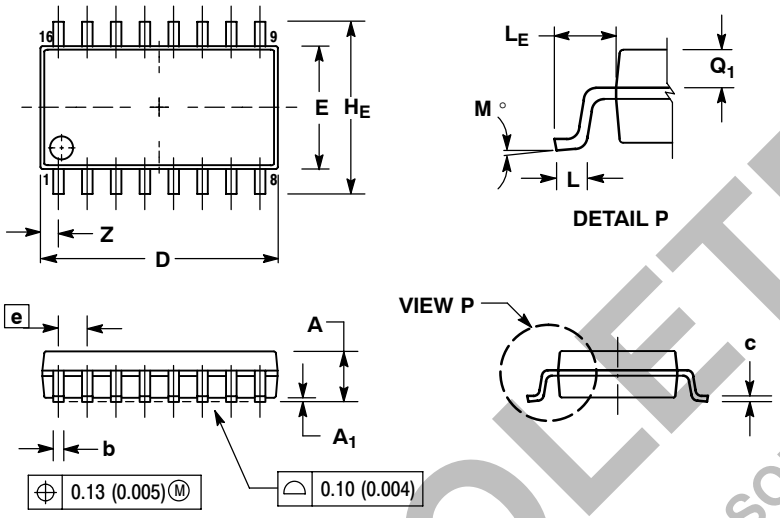


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

M SUFFIX
SOEIAJ PACKAGE
CASE 966−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

PUBLICATION ORDERING INFORMATION

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